



RADSOK® RadFin™

BACKGROUND

Higher integration of power hungry components are driving PCB power requirements to new levels. Low voltage IC packages running at faster speeds are creating the need for delivering more than 100A on high performance PCBs used in data center equipment.

PROBLEM

With compromises that must be weighed at the onset design of component placement on the PCB, power delivery systems must be flexible and deliver large currents using a minimum of PCB real estate. Single point power connectors can be placed to optimize power delivery without interfering with high speed signal routing.

AIPG SOLUTION

The Amphenol Industrial Products Group offers a line of RadFin power connectors using our patented RADSOK® contact technology to meet the increasing power requirements on the board in a smaller board footprint. The right angle receptacle is a single-point contact which gives the versatility needed when component placement decisions are crucial. Available in solder tail, compliant pin and screw mount the RadFin can deliver up to 300A in less than 1 linear inch of card edge.

